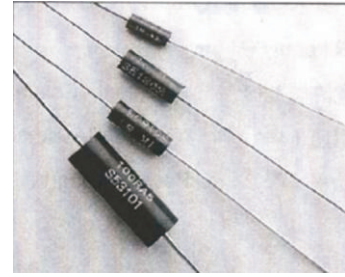




■ 特性 Feature

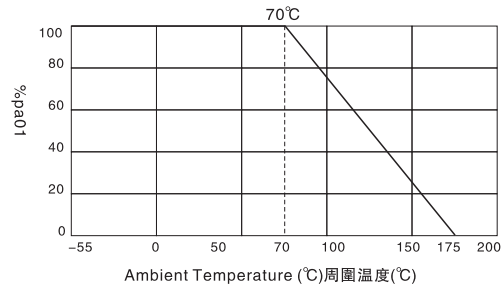
- 模壓封裝  
Mould pressing encapsulation
- 高穩定、高可靠性  
High steady, high dependability
- 精密的誤差從 ±0.01%~±0.5%  
Very tight tolerance from ±0.01%~ ±0.5%
- 極低的溫度係數 ±5~±50PPM/°C  
Extremely low TCR from ±5~±50 PPM/°C



■ 尺寸 Dimension



■ 降功率曲線 Derating Curve



Type	Dimension (mm)				Max. Working Voltage	Max. Overload Voltage	Dielectric Withstanding Voltage	Resistance Range	Tolerance
	Mould pressing Size	L ± 0.5	D ± 0.5	∅d ± 0.05					
1/8W	4.3	1.9	0.43	27	200V	400V	500V	10Ω~1 MΩ	D: ±0.5% C: ±0.25% B: ±0.1% A: ±0.05% T: ±0.01%
1/4W	6.8	2.5	0.50	27	200V	400V	500V	10Ω~3 MΩ	
1/2W	10.2	3.8	0.60	26	250V	500V	500V	10Ω~5 MΩ	
3/4W	15.1	5.2	0.80	28	300V	600V	500V	10Ω~10MΩ	
1W	18.4	6.5	0.8	34	350V	700V	500V	10Ω~10MΩ	

☞ 可根據客戶提出的溫度係數要求制作。

☞ R≤10 Ω 的電阻器最小阻值允許偏差 ± 0.1% 若用戶需要5 Ω~3MΩ的電阻器阻值允許偏差可以做到 ± 0.01%。

■ 性能和測試要求 Specification And Test Methods

Operating Temperature	-55°C~+175°C
Temperature coefficient	± 50PPM/°C、± 25PPM/°C、± 15PPM/°C、± 5PPM/°C, Make in accordance with customer's demand
Short-time overload	± (0.1% + 0.05Ω) Max.
Insulation resistance	≥ 1,000 Mega Ohm
Dielectric withstanding voltage	No evidence of flashover, mechanical damage, arcing or insulation breakdown
Terminal bending	± (0.1% + 0.05Ω) Max.
Soldering heat	± (0.1% + 0.05Ω) Max.
Solder ability	Min 95% coverage
Temperature cycling	± (0.1% + 0.05Ω) Max.
Humidity (Steady State)	± (0.5% + 0.1Ω) Max.
Load life	± (0.5% + 0.1Ω) Max.